

**STACKED ELECTRONIC STRUCTURES INCLUDING OFFSET  
SUBSTRATES**

**Abstract**

An electronic device may include first, second, and third substrates wherein

5 the second electronic substrate is between the first and second electronic substrates. A first electrical and mechanical connection may be provided between the first and third electronic substrates, and a second electrical and mechanical connection may be provided between the second and third electronic substrates. In addition or in an alternative, an electronic device may include a printed circuit

10 board, a first electronic substrate on the printed circuit board, a second electronic substrate on the first electronic substrate, and a third electronic substrate on the second electronic substrate. More particularly, the first electronic substrate may be between the printed circuit board and the second electronic substrate, and the second electronic substrate may be between the first and third electronic substrates.

15 In addition, the second electronic substrate may be offset relative to the first and third electronic substrates so that a first end of the second electronic substrate extends beyond the first and third electronic substrates and so that the first and third electronic substrates extend beyond a second end of the second electronic substrate.